

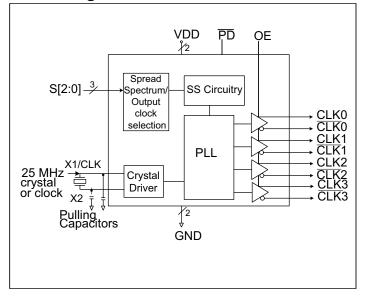


#### Low Power PCIe 3.0 Clock Generator with 4 HCSL Outputs

#### **Features**

- $\rightarrow$  PCIe<sup>®</sup> 3.0, 2.0 and 1.0 complaint
- →LVDS compatible outputs
- → Supply voltage of  $3.3V \pm 5\%$
- $\rightarrow$  25MHz crystal or clock input frequency
- $\rightarrow$  Low power consumption with independent output power supply 1.05V to 3.3V
- $\rightarrow$  Jitter 40ps cycle-to-cycle (typ)
- $\rightarrow$  Spread of -0.5%, -1.0%, -1.5%, and no spread
- $\rightarrow$  Industrial temperature range
- → Spread Bypass option available
- $\rightarrow$  Spread and frequency selection via external pins
- → Packaging: (Pb-free and Green)
  - 20-pin, 173-mil wide TSSOP

#### **Block Diagram**

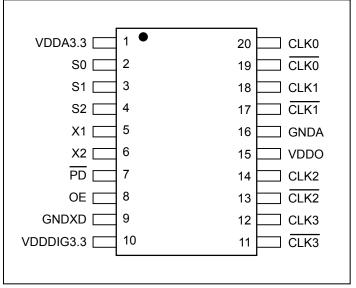


## Description

The PI6CFGL402B is a spread spectrum clock generator compliant to PCI Express® 3.0 and Ethernet requirements. The device is used for PC or embedded systems to substantially reduce Electromagnetic Interference (EMI).

The PI6CFGL402B provides four differential (HCSL) or LVDS spread spectrum outputs. The PI6CFGL402B is configured to select spread and clock selection. Using Diodes' patented Phase-Locked Loop (PLL) techniques, the device takes a 25MHz crystal input and produces four pairs of differential outputs (HCSL) at 100MHz and 200MHz clock frequencies. It also provides spread selection of -0.5%, -1.0%, -1.5%, and no spread.

### Pin Configuration







## **Pin Description**

Pin #	Pin Name	I/O Type	Description
1	VDDA3.3	Power	3.3V power for PLL core.
2	SO	Input	Spread Spectrum Select pin #0. See Spread Selection Table. Internal pull-up resistor.
3	S1	Input	Spread Spectrum Select pin #1. See Spread Selection Table. Internal pull-up resistor.
4	S2	Input	Spread Spectrum Select pin #2. See Spread Selection Table. Internal pull-up resistor.
5	X1	Input	Crystal connection.
6	X2	Output	Crystal connection.
7	$\overline{PD}$	Input	Power down. Internal pull-up resistor.
8	OE	Input	Output enable. Tri-states output (High=enable outputs); Low=disable outputs). Internal pull-up resister.
9	GNDXD	Power	Connect to digital circuit ground.
10	VDDDIG3.3	Power	3.3V digital power.
11	CLK3	Output	Selectable 100/200 MHz Spread Spectrum differential compliment output clock 3. LOW when output is disabled.
12	CLK3	Output	Selectable 100/200 MHz Spread Spectrum differential true output clock 3. LOW when output is disabled.
13	CLK2	Output	Selectable 100/200 MHz Spread Spectrum differential compliment output clock 2. LOW when output is disabled.
14	CLK2	Output	Selectable 100/200 MHz Spread Spectrum differential true output clock 2. LOW when output is disabled.
15	VDDO	Power	Output power supply, nominal 1.8V, range 1.05V~3.3V.
16	GNDA	Power	Output and Analog circuit ground
17	CLK1	Output	Selectable 100/200 MHz Spread Spectrum differential compliment output clock 1. LOW when output is disabled.
18	CLK1	Output	Selectable 100/200 MHz Spread Spectrum differential true output clock 1. LOW when output is disabled.
19	CLK0	Output	Selectable 100/200 MHz Spread Spectrum differential compliment output clock 0. LOW when output is disabled.
20	CLK0	Output	Selectable 100/200 MHz Spread Spectrum differential true output clock 0. LOW when output is disabled.

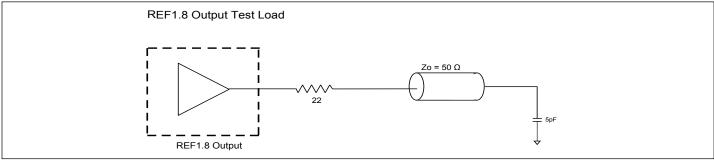
#### **Table 2: Spread Selection Table**

S2	\$1	<b>S0</b>	Spread %	Spread Type	Output Frequency
0	0	0	-0.5	Down	100
0	0	1	-1.0	Down	100
0	1	0	-1.5	Down	100
0	1	1	No Spread	Not Applicable	100
1	0	0	-0.5	Down	200
1	0	1	-1.0	Down	200
1	1	0	-1.5	Down	200
1	1	1	No Spread	Not Applicable	200

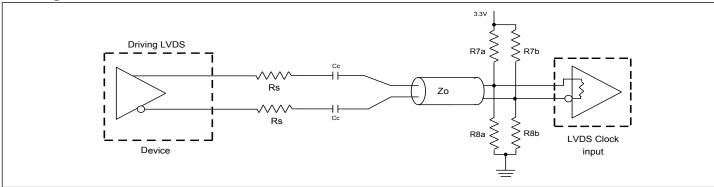




### **Test Loads**



## **Driving LVDS**



## **Driving LVDS inputs with the PI6CFGL402B**

	Value			
Component	Receiver has termination	Receiver does not have termination		
R7a, R7b	10Κ Ω	140 Ω		
R8a, R8b	5.6Κ Ω	75 Ω		
Cc	0.1 uF	0.1 uF		
Vcm	1.2 volts	1.2 volts		





## **Maximum Ratings**

(Above which useful life may be impaired. For user guidelines, not tested.)

Supply Voltage to Ground Potential	4.6V
All Inputs and Output	0.5V toVDD+0.5V
Ambient Operating Temperature	-40 to +85°C
Storage Temperature	65°C to +150°C
Junction Temperature	125°C
Soldering Temperature	
ESD Protection (Input)	2000V(HBM)

Note: Stresses greater than those listed under MAXIMUM RAT-INGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

# **Electrical Characteristics–Current Consumption**

 $(T_A = -40 \sim 85^{\circ}C; Supply Voltage VDD = 3.3V + /-10\%; VDDO = 1.8V + /-10\%, See Test Loads for Loading Conditions)$ 

Symbol	Parameters	Condition	Min.	Тур.	Max.	Units
I <sub>DDOP</sub>	Operating Supply Current <sup>1</sup>	Total power consumption, All outputs active @100MHz			60	mA

Notes:

1. Guaranteed by design and characterization, not 100% tested in production.

# Electrical Characteristics-Input/Supply/Common Parameters-Normal Operating

**Conditions** ( $T_A = -40 \sim 85^{\circ}$ C; Supply Voltage VDD = 3.3V +/-10%; VDDO = 1.8V +/-10%, See Test Loads for Loading Conditions)

Symbol	Parameters	Condition	Min.	Тур.	Max.	Units
V <sub>DDX</sub>	Supply Voltage <sup>1</sup>	Supply voltage for core, analog	3.0	3.3	3.6	V
V <sub>DDO</sub>	Supply Voltage <sup>1</sup>	Supply voltage outputs	1.65	1.8	2.0	V
V <sub>IH</sub>	Input High Voltage <sup>1</sup>	OE, S0, S1, S2	0.65 V <sub>DD</sub>		V <sub>DD</sub> + 0.3	V
V <sub>IL</sub>	Input Low Voltage <sup>1</sup>	OE, S0, S1, S2	-0.3		0.35 V <sub>DD</sub>	V
I <sub>IN</sub>		Single-ended inputs, $V_{IN}$ = GND, $V_{IN}$ = VDD (exclude XTAL pin)	-5		5	uA
I <sub>INP</sub>	Input Current <sup>1</sup>	Single-ended inputs $V_{IN} = 0$ V; Inputs with internal pull-up resistors $V_{IN} = VDD$ ; Inputs with internal pull-down resis- tors	-200		200	uA
Fin	Input Frequency <sup>1</sup>	XTAL, or X1 input	23	25	27	MHz
Lpin	Pin Inductance <sup>1</sup>				7	nH
C <sub>IN</sub>		Logic Inputs, except DIF_IN	1.5		5	pF
C <sub>INDIF_IN</sub>	Capacitance <sup>1,4</sup>	DIF_IN differential clock inputs	1.5		2.7	pF
COUT		Output pin capacitance			6	pF





Symbol	Parameters	Condition	Min.	Тур.	Max.	Units
T <sub>STAB</sub>	Clk Stabilization <sup>1,2</sup>	From V <sub>DD</sub> Power-Up and after input clock stabilization or de-assertion of PD# to 1st clock		0.6	1	ms
f <sub>MODIN</sub>	Input SS Modulation Frequency <sup>1</sup>	Allowable Frequency (Triangular Modulation)	30 31.500		33	kHz
t <sub>OE</sub>	Output Enable Time <sup>1</sup>	All outputs			10	μs
t <sub>OT</sub>	Output Disable Time <sup>1</sup>	All outputs			10	μs
t <sub>STABLE</sub>	From power-up to $V_{DD} = 3.3 V^1$	From Power-up $V_{DD} = 3.3V$		3.0		ms
t <sub>SPREAD</sub>	Setting period after spread change <sup>1</sup>	Setting period after spread change		3.0		ms

Note:

1. Guaranteed by design and characterization, not 100% tested in production.

2. Control input must be monotonic from 20% to 80% of input swing. Input Frequency Capacitance

3. Time from deassertion until outputs are >200 mV

4. DIF IN input

### Electrical Characteristics–CLK 0.7V Low Power HCSL Outputs ( $T_A = -40 \sim 85^{\circ}C$ ; Supply Voltage VDD

= 3.3V +/-10%; VDDO = 1.8V +/-10%; 100MHz output frequency, See Test Loads for Loading Conditions)

Symbol	Parameters	Condition		Тур.	Max.	Units
Trf	Slew rate <sup>1,2,3</sup>		1.1	2	4.5	V/ns
V <sub>HIGH</sub>	Voltage High <sup>1</sup>	Statistical measurement on single-ended signal	660		950	mV
V <sub>LOW</sub>	Voltage Low <sup>1</sup>	using oscilloscope math function. (Scope aver- aging on)	-150		150	mV
Vmax	Max Voltage <sup>1</sup>	Measurement on single ended signal using			1150	mV
Vmin	Min Voltage <sup>1</sup>	absolute value. (Scope averaging off)	-300			mV
Vswing	Vswing <sup>1,2</sup>	Scope averaging off	300			mV
Vcross_abs	Crossing Voltage (abs) <sup>1,5</sup>	Scope averaging off	250		550	mV
Δ-Vcross	Crossing Voltage (var) <sup>1,6</sup>	Scope averaging off			140	mV
t <sub>DC</sub>	Duty Cycle <sup>1</sup>	Measured differentially, PLL Mode	45		55	%
t <sub>skew</sub>	Skew, Output to Output <sup>1</sup>	V <sub>T</sub> = 50%			50	ps
t <sub>jcyc-cyc</sub>	Jitter, Cycle to cycle <sup>1,2</sup>	PLL mode			50	ps

Note:

1. Guaranteed by design and characterization, not 100% tested in production.

2. Measured from differential waveform

<sup>3.</sup> Slew rate is measured through the Vswing voltage range centered around differential 0V. This results in a +/-150mV window around differential 0V.

<sup>4.</sup> Matching applies to rising edge rate for Clock and falling edge rate for Clock#. It is measured using a +/-75mV window centered on the average cross point where Clock rising meets Clock# falling. The median cross point is used to calculate the voltage thresholds the oscilloscope is to use for the edge rate calculations.

<sup>5.</sup> Vcross is defined as voltage where Clock = Clock# measured on a component test board and only applies to the differential rising edge (i.e. Clock rising and Clock# falling).

<sup>6.</sup> The total variation of all Vcross measurements in any particular system. Note that this is a subset of Vcross\_min/max (Vcross absolute) allowed. The intent is to limit Vcross induced modulation by setting Δ-Vcross to be smaller than Vcross absolute.





## **Electrical Characteristics–Phase Jitter Parameters**

(T<sub>A</sub> = -40~85°C; Supply Voltage VDD = 3.3V +/-10%; VDDO = 1.8V +/-10%; 100MHz output frequency, See Test Loads for Loading Conditions)

Symbol	Parameters	Parameters Condition		Тур.	Industry Limit	Units
tjphPCIeG1		PCIe Gen 1 <sup>1,2,3,5</sup>		25	86	ps (p-p)
Phase Ji	Phase Jitter,	PCIe Gen 2 Low Band $10$ kHz < f < $1.5$ MHz <sup>1,2,5</sup>		0.9	3	ps (rms)
tjphPCIeG2	PCI Express	PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz) <sup>1,2,5</sup>		1.6	3.1	ps (rms)
tjphPCIeG3		PCIe Gen 3 (PLL BW of 2-4MHz, CDR = 10MHz) <sup>1,2,4,5</sup>		0.36	1	ps (rms)

Notes:

1. Guaranteed by design and characterization, not 100% tested in production.

2. See http://www.pcisig.com for complete specs.

3. Sample size of at least 100k cycles. This figures extrapolates to 108ps pk-pk @ 1M cycles for a BER of 1-12.

4. Calculated from Intel-supplied Clock Jitter Tool.

5. Applies to all different outputs.



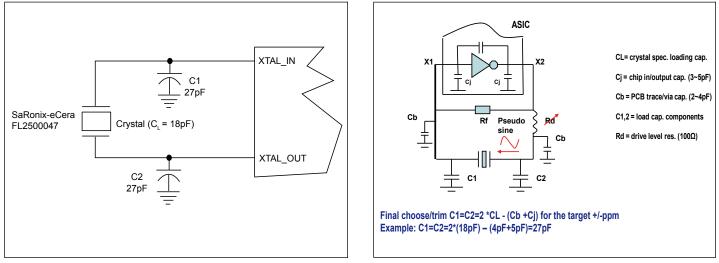


## **Application Notes**

## **Crystal circuit connection**

The following diagram shows crystal circuit connection with a parallel crystal. For the CL=18pF crystal, it is suggested to use C1= 27pF, C2= 27pF. C1 and C2 can be adjusted to fine tune to the target ppm of crystal oscillator according to different board layouts.

## **Crystal Oscillator Circuit**



# **Recommended Crystal Specification**

**Diodes Recommends:** 

- a) FY2500081, SMD 5x3.2(4P), 25M, CL=18pF, +/-30ppm, https://www.diodes.com/assets/Datasheets/FYF9.pdf
- b) FL2500047, SMD 3.2x2.5(4P), 25M, CL=18pF, +/-20ppm, https://www.diodes.com/assets/Datasheets/FL.pdf

## **Part Marking**

L Package

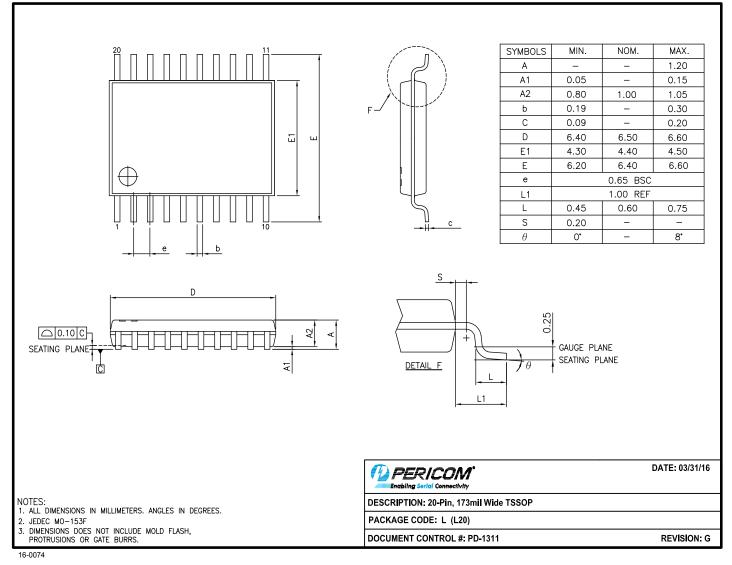


1st Y: Die Rev YY: Year WW: Workweek 1st X: Assembly Code 2nd X: Fab Code





### Packaging Mechanical: 20-TSSOP (L)



#### For latest package info.

please check: http://www.diodes.com/design/support/packaging/pericom-packaging/packaging-mechanicals-and-thermal-characteristics/

## Ordering Information<sup>(1-3)</sup>

Ordering Code	Package Code	Description
PI6CFGL402BLIEX	L	20-Pin, 173mil Wide (TSSOP)

Notes:

1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.

2. See http://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free. Thermal characteristics can be found on the company web site at www.diodes.com/design/support/packaging/

3. E = Pb-free and Green

4. X suffix = Tape/Reel





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